

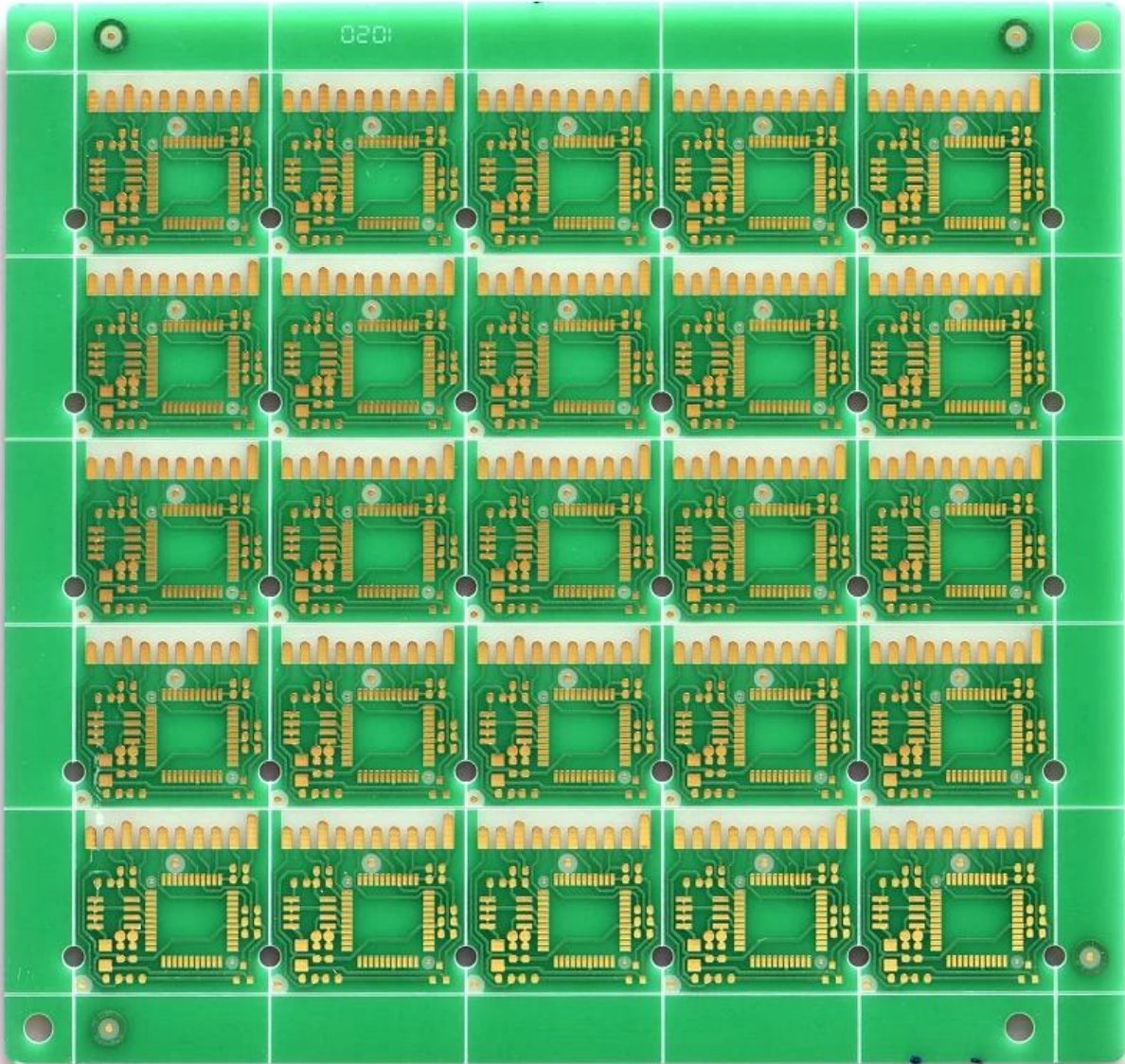
O-LEADING
To Be Reliable, To Be Valuable

QUALITY IS OUR CULTURE

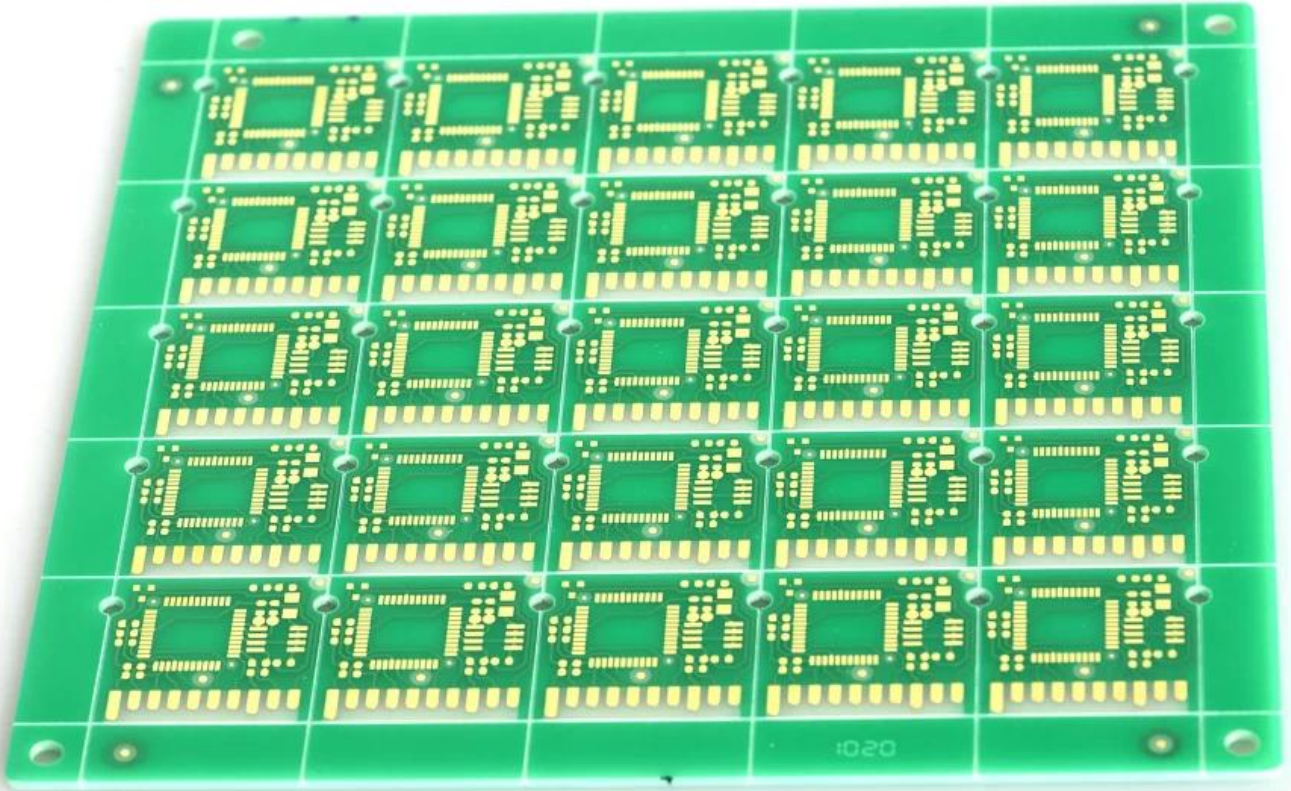


O-LEADING

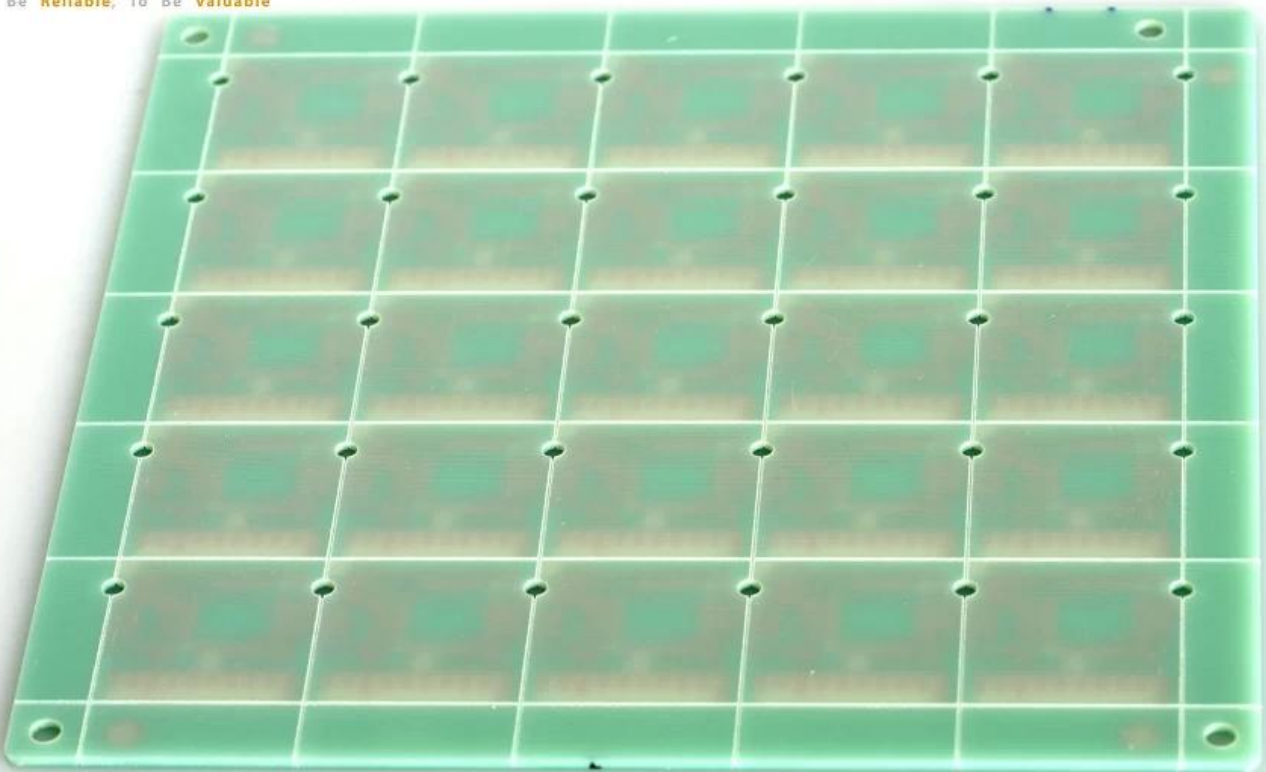
To Be Reliable, To Be Valuable

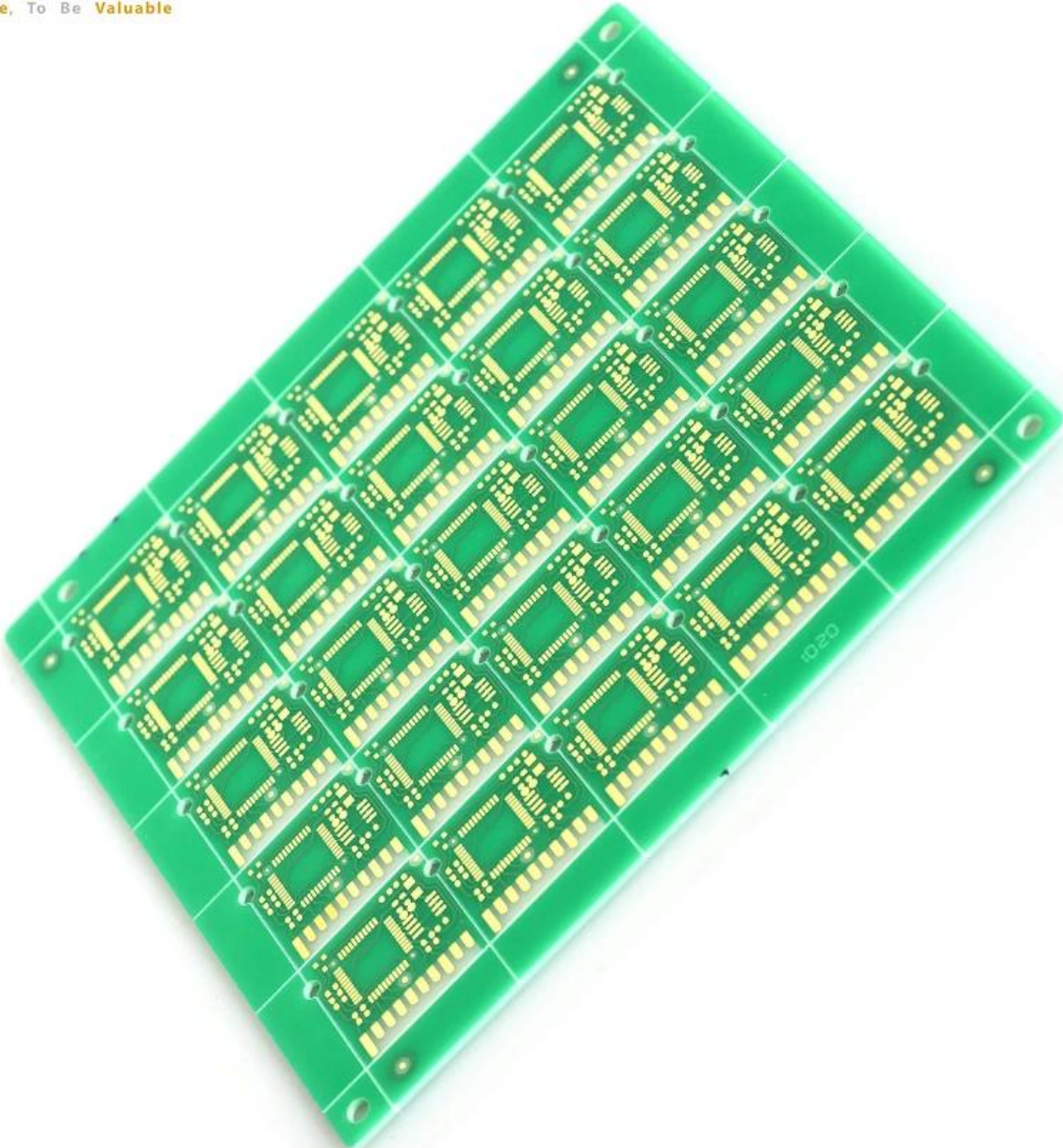


O-LEADING
To Be Reliable, To Be Valuable



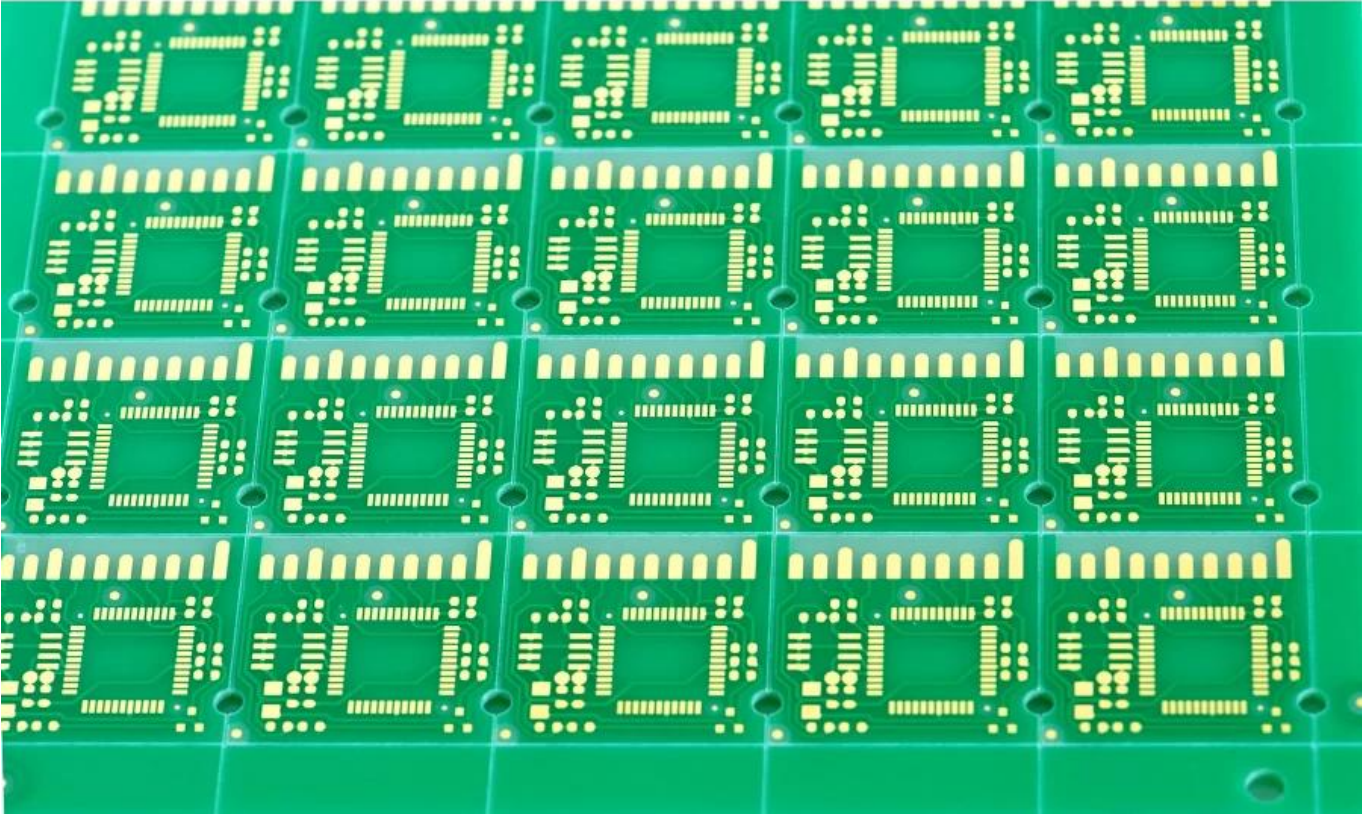
O-LEADING
To Be Reliable, To Be Valuable





O-LEADING

To Be **Reliable**, To Be **Valuable**



Production Process

18 years experience in one-stop PCB and PCBA, we can make your idea come true,



 CONSUMER ELECTRONICS

 AUTOMOTIVE ELECTRONICS

 INDUSTRIAL CONTROL

 INTELLECTUALIZED HOUSEHOLD CONTROL

 OTHER



30%
CONSUMER ELECTRONICS



18%
INTELLECTUALIZED HOUSEHOLD CONTROL

20%
AUTOMOTIVE ELECTRONICS



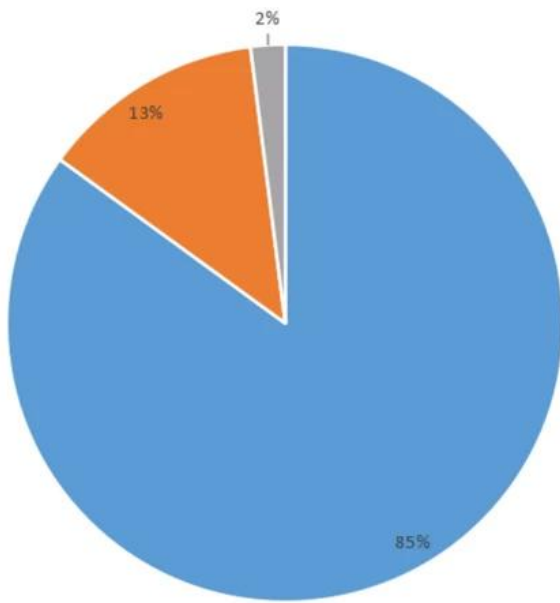
12%
OTHER



20%
INDUSTRIAL CONTROL



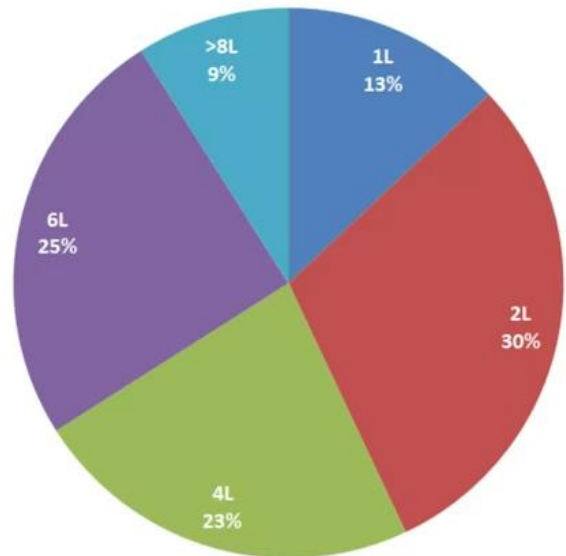
Product types



■ FR-4 PCB ■ MC PCB ■ rigid-flexible PCB

Product layers

■ 1L ■ 2L ■ 4L ■ 6L ■ >8L





Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT





CICC INSPECTION CERTIFICATION



嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R05

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No: 61691591-000-07-18-7

Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK

Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification
Sales of printed circuit boards

Initial issuance period: February 27, 2018
Renewal date: April 22, 2019
This certificate is valid during: April 22, 2019 – February 26, 2021
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
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The certificate registration fee does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the client. The effectiveness of this certificate shall be restricted to those activities which are covered by the certificate. The initial issuance of this certificate can be restricted on the period of 120 days after the date of issuance.






CICC INSPECTION CERTIFICATION



嘉泰认证

质量管理体系认证证书

证书号: 18118Q10347R05

兹证明

诚领供应链(香港)有限公司

统一社会信用代码: 61691591-000-07-18-7
注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室
经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

建立的质量管理体系符合
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

认证范围
印刷线路板的销售

初次获证日期: 2018年02月27日
换证日期: 2019年04月22日
证书有效期: 自2019年04月22日至2021年02月26日
在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

第一次复审	第二次复审	黏贴处
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本证书认证范围不包括未获得有效的国家规定的行政许可、资质许可的产品/服务范围; 本证书通过CICC定期监督审核保持, 与年度《保持认证通知书》共同方为有效; 本证书信息可在国家认监委网站: www.cnca.gov.cn及CICC网站www.cicc.com.cn查询。








ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width			SS/ DS/ DSO	Max	Max			Meets UL796	C T	
	Min	Cond	Area		Solder	Flame	Class				
	Min	Edge			Limits			Oper			
mm(in)	mm(in)	Thk mic(mil)	Diam mm(in)	C	sec	C	DSR	I			
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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PCB	
Layer Count	1-32
Weight	1 / 3oz-12oz
Copper Thickness	3.0mil / 3.0mil
Prepreg Thickness	4.0mil / 4.0mil
Aspect Ratio	10 : 1
Core Thickness	0.2mm-5.0mm
Core Size (mm)	635 * 1500mm
Core Thickness	4mil
Plated Thickness	+/- 3mil
Blind / Buried Vias (All)	
Blind / Buried Vias (All)	
Material	FR-4, FR-4high Tg, FR-5, FR-6, FR-7, FR-8, FR-9, FR-10, FR-11, FR-12, FR-13, FR-14, FR-15, FR-16, FR-17, FR-18, FR-19, FR-20, FR-21, FR-22, FR-23, FR-24, FR-25, FR-26, FR-27, FR-28, FR-29, FR-30, FR-31, FR-32, FR-33, FR-34, FR-35, FR-36, FR-37, FR-38, FR-39, FR-40, FR-41, FR-42, FR-43, FR-44, FR-45, FR-46, FR-47, FR-48, FR-49, FR-50, FR-51, FR-52, FR-53, FR-54, FR-55, FR-56, FR-57, FR-58, FR-59, FR-60, FR-61, FR-62, FR-63, FR-64, FR-65, FR-66, FR-67, FR-68, FR-69, FR-70, FR-71, FR-72, FR-73, FR-74, FR-75, FR-76, FR-77, FR-78, FR-79, FR-80, FR-81, FR-82, FR-83, FR-84, FR-85, FR-86, FR-87, FR-88, FR-89, FR-90, FR-91, FR-92, FR-93, FR-94, FR-95, FR-96, FR-97, FR-98, FR-99, FR-100
Surface Finish	HASL, OSP, ENIG, HAL-LF, Ni-Au, Ni-P, Ni-Cu, Ni-Fe, Ni-Mo, Ni-W, Ni-Zn, Ni-Co, Ni-Si, Ni-B, Ni-S, Ni-P, Ni-Cu, Ni-Fe, Ni-Mo, Ni-W, Ni-Zn, Ni-Co, Ni-Si, Ni-B, Ni-S

SMT	
PCB Material	FR-4, CEM-1, CEM-3, FR-5, FR-6, FR-7, FR-8, FR-9, FR-10, FR-11, FR-12, FR-13, FR-14, FR-15, FR-16, FR-17, FR-18, FR-19, FR-20, FR-21, FR-22, FR-23, FR-24, FR-25, FR-26, FR-27, FR-28, FR-29, FR-30, FR-31, FR-32, FR-33, FR-34, FR-35, FR-36, FR-37, FR-38, FR-39, FR-40, FR-41, FR-42, FR-43, FR-44, FR-45, FR-46, FR-47, FR-48, FR-49, FR-50, FR-51, FR-52, FR-53, FR-54, FR-55, FR-56, FR-57, FR-58, FR-59, FR-60, FR-61, FR-62, FR-63, FR-64, FR-65, FR-66, FR-67, FR-68, FR-69, FR-70, FR-71, FR-72, FR-73, FR-74, FR-75, FR-76, FR-77, FR-78, FR-79, FR-80, FR-81, FR-82, FR-83, FR-84, FR-85, FR-86, FR-87, FR-88, FR-89, FR-90, FR-91, FR-92, FR-93, FR-94, FR-95, FR-96, FR-97, FR-98, FR-99, FR-100
PCB Size	510x460mm
PCB Size	50x50mm
PCB Thickness	0.5mm-4.5mm
PCB Thickness	0.5-4mm
PCB Thickness	0201
PCB Thickness	0603
PCB Thickness	15mm
PCB Thickness	0.3mm
PCB BGA Thickness	0.4mm
PCB Thickness	+/- 0.03mm



Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days



1. O-Leading 0000 0000 0000000?

0000 0000 0000 0000 00 0000000.

1.1 0000 ISO 9001 : 2008 0000 00 0000 0000000.

1.2 00 00 00000 00000000 00000 00

1.3 0000 0000 00 0 00. 0 : 0000 0000, X-ray 00, AOI (Automated Optical Inspector) 0 ICT (in-circuit testing).

1.4 00 00 00 000000 00 00 00 00 0

1.5. 00000 00 00 0 00

2. O-Leading 0000 00 000000 0000000?

00 10 0 00 00 0000 (0 : 00, 00 00)0 0000 0 0, 0 0 00 0 00 0000000. 00 00 00000 00 00000 31 % 0000000. 00 0000 00 0000000.

0000 O-Leading0 0000 0000000 0000000. 00 00 00, 0000 00 0 0000 0000000 0000 00000 00 00000. 0000 0000 0000 00 00000 0 0000 00 00000 00000.

0000 00000 00 0000000 00000. 0000 0000 0000000 0000 0000 00 0 0 0000 0000 0000000 00 0000 0 00000.

3. O-Leading 00 0000 0000 00 0 0 00000?

00 FR4, 0 TG 0 0 0000 00, Rogers, Arlon, Telfon, 00000 / 00 00 00, PI 0

4. PCB 及 PCBA 的製造過程是什麼?

- 4.1 物料清單 BOM (Bill of Materials) : 物料清單, 物料清單表 及 物料清單表.
- 4.2 PCB 的製造.
- 4.3 PCB 的組裝 及 PCBA 的組裝.
- 4.4 測試.
- 4.5 物料清單 及 物料清單表 的比較.

5. PCB 的製造過程是什麼?

物料清單 → 物料清單表 → 物料清單表 → PCB AOI → 物料清單表 → 物料清單表 → PTH → 物料清單表 → 物料清單表 → 物料清單表 → 物料清單表 → PCB AOI → 物料清單表 → 物料清單表 → 物料清單表 → 物料清單表 → E / T → 物料清單表.

6. HDI 的製造過程是什麼?

物料清單 及 物料清單表 : 物料清單表, 物料清單表, VCP 物料清單表, 物料清單表, LDI 物料清單表. 物料清單表 及 物料清單表, 物料清單表 Mitsubishi Hitachi, LDI 物料清單表 Screen (Japan), 物料清單表 Hitachi 物料清單表, 物料清單表 及 物料清單表 物料清單表.

7. O-lead 的製造過程是什麼?

O-lead ENIG, OSP, LF-HASL, 物料清單 (物料 / 物料), 物料清單, 物料清單, 物料清單表, 物料清單表 及 物料清單表. HDI 物料清單表 物料清單表 OSP, ENIG, OSP + ENIG, BGA PAD 物料清單 0.3 mm 物料清單表 物料清單表 物料清單表 OSP OSP + ENIG 物料清單表 物料清單表.

8. FPC 的製造過程是什麼? O-Leading 及 SMT 的製造過程是什麼?

O-Leading 物料清單表 8 物料清單 FPC 物料清單表 物料清單, 物料清單表 2000mm * 240mm 物料清單表. 物料清單表 "Flex Capability" 物料清單表. 物料清單表 SMT 物料清單表 物料清單表.

9. PCB 的製造過程是什麼?

- 物料;
- 物料;
- 物料;
- 物料 物料;
- PCB 物料;
- 物料;
- 物料 物料.

10. PCB, PWB 及 FPC 的製造過程是什麼?

PCB 物料 物料 物料 物料. PWB 物料 物料 (Printed Wire Board) 物料 物料 物料 物料 物料. FPC Flexible Printed Board 物料.

11. PCB 的製造過程是什麼?

PCB 物料 物料 物料 物料 物料. 物料 Tg 物料 物料 物料. 物料 CTE 物料 物料 物料 物料 物料; 物料 物料 : 物料 PCB 物料 50 物料 250 °C 物料. 物料 物料; 物料 物料 物料 物料 / 物料 物料 物料 PCB 物料. 物料 PCB 物料 物料 物料 物料 物料; 物料 物料 物料 物料 物料 物料 物料.

12. O-leading 的 PCB 的製造過程是什麼?

O-leading 物料 物料 PCB FPC PCB 物料 物料 物料 物料 物料. 物料 物料 物料 物料 物料 物料 物料 物料 物料 物料.

13. 物料 物料 物料 物料?

□□□□ □□ □□□□ □□ □□□□ □□, SI6000 soft □ POLAR INSTRUMENTS□ CITS 500s □□□□ □□□□□□.
□□□□ □□□□ □□ □□□□ □□ □□□□ □□ □□□□ □□□□□□ □□□□□□.